

Description

The present invention relates generally to the manufacture of integrated circuits. In particular, the present invention is a method for manufacturing flexible thin-film integrated circuits to prevent stress on the layer of semiconductor material when the circuit is flexed.

Integrated circuits are well known and can be manufactured using any of a number of known techniques. Thin-film solar cells, for example, can be inexpensively manufactured by depositing layers of semiconductor material on flexible substrates using glow discharge deposition and roll-to-roll processing techniques. Continuous roll processing on flexible, aluminum, stainless steel, tantalum, molybdenum, chrome, polyimide-coated stainless steel and polyimide substrates is known. Since solar cells fabricated on these substrates are flexible, they can be mounted to nonplanar objects. In an embodiment described in these substrates are flexible, they can be mounted to nonplanar objects. In an embodiment described in US-application Serial No. 07/165,488, entitled "Light-Rechargeable Battery", filed March 8, 1988 and assigned to the same assignee as the present invention, flexible solar cells are mounted to the cylindrical surface of a battery so as to recharge the battery when it is positioned in ambient light.

Thin-film solar cells are flexed and bent when rolled up following their manufacture or applied to nonplanar articles. One side of the flexed solar cell will be subjected to compressive forces while the opposite side will be stretched and placed in tension. If the semiconductor region or layer forming the solar cell photovoltaic device is at a location which is placed in either tension or compression, its electrical and physical properties can be detrimentally affected. It is known that bond distances in the semiconductor material can be altered and broken by these forces. The result is reduced solar cell efficiency.

The present invention is an improved method for manufacturing integrated circuits of the type having a flexible substrate, a layer of semiconductor material on the substrate, and an encapsulant layer over the semiconductor material. The improvement is characterized by selecting thickness of the flexible substrate and/or the encapsulant layer as a function of the elastic moduli of the substrate and encapsulant layer so that the neutral plane (neutral stress/strain plane) of the integrated circuit is located near the layer of semiconductor material. Damaging stresses on the layer of semiconductor material are thereby prevented when the integrated circuit is flexed.

Figure 1 is an illustration of a strip of solar cell tape manufactured in accordance with the present invention.

Figure 2 is an illustration of a solar cell manufactured in accordance with the present invention.

An integrated circuit such as a strip of solar cell tape 10 manufactured in accordance with the present invention is illustrated generally in Figure 1. Solar cell tape 10 includes a thin-film semiconductor photovoltaic device 5 fabricated on a flexible substrate 3. An upper or active surface of photovoltaic device 5, the surface opposite substrate 3, is encapsulated by an optically transparent glazing 1. A layer of adhesive 2 can be used to bond glazing 1 to photovoltaic device 5. A layer of adhesive 4 is applied to a lower surface of substrate 3, opposite photovoltaic device 5. Solar cell tape 10 can thereby be adhesively affixed to a variety of objects. During manufacture, the thickness of glazing 1, layers of adhesive 2 and 4, and substrate 3 are selected as a function of their flexural or elastic moduli so the neutral plane of solar cell tape 10 is located at the plane in which photovoltaic device 5 is located. Subsequent flexing of solar cell tape 10, as for example when it is rolled after manufacture or applied to a nonplanar article, will therefore result in minimal amounts of stress to photovoltaic device 5 and prevent detrimental flexion-caused physical and electrical effects.

Known manufacturing techniques including chemical vapor deposition during roll-to-roll processing can be used to fabricate photovoltaic device 5 on substrate 3. Substrate 3 can be any flexible substrate having electrical and physical properties appropriate for the intended application. Conductive substrates such as thin stainless steel and insulating substrates such as polyimide are commonly used. In one embodiment photovoltaic device 5 is an amorphous silicon device fabricated on a polyimide substrate 3. Transparent glazing 1 can be any of a wide variety of known polymeric, solar cell encapsulants such as polyethylene, polypropylene, polyester, poly(methyl) methacrylate (PMMA), ethyl vinyl acetate, or butyl acrylate. Glazing 1 can be bonded to photovoltaic device 5 using any known adhesive 2 having appropriate optical and electrical properties. In one embodiment an impact-modified PMMA layer of glazing 1 is bonded to photovoltaic device 5 using a silicone-based or acrylic-based layer of adhesive 2. In other embodiments (not shown), transparent glazing 1 can be direct-coated or thermal-bonded to photovoltaic device 5 without the need for a layer of adhesive 2. Adhesive 4 can be any known adhesive, such as pressure sensitive adhesives (PSAs), having appropriate properties.

As shown in Figure 1, transparent glazing 1, layer of adhesive 2, substrate 3, and layer of adhesive 4 are all characterized by an elastic or flexural modulus E_1 , E_2 , E_3 , and E_4 , and a thickness t_1 , t_2 , t_3 , and t_4 , respectively. Elastic moduli, also known as Young's moduli, are measures of the stiffness of the materials.

Elastic moduli E_1 - E_4 (i.e., E_1 , E_2 , E_3 and/or E_4) characterize the ratio of stress to corresponding strain when the associated material behaves elastically. Typical or characteristic elastic moduli E for a variety of materials are listed below:

STAINLESS STEEL	30×10^6 psi (1 psi = 6.895×10^3 Nm ⁻²)
POLYMERS	1×10^3 - 1×10^6 psi
POLYIMIDE	3×10^5 psi
GLAZING	1×10^3 - 1×10^5 psi

The present invention is based upon the realization that by selecting the thicknesses t_1 - t_4 (i.e., t_1 , t_2 , t_3 and/or t_4) of the associated layers of materials 1-4 (i.e., materials 1, 2, 3 and/or 4) as a function of their respective elastic moduli E_1 - E_4 , solar cell tape 10 can be manufactured with its neutral (stress/strain) plane or moment located at the layer of photovoltaic device 5. Subsequent flexing of solar cell tape 10 will then result in no stress or strain within photovoltaic device 5, even as the layers of materials 1-4 on opposite sides of photovoltaic device 5 are subject to tensile and compressive forces. Electrical and physical characteristics of photovoltaic device 5 will therefore be unaffected when solar cell tape 10 is flexed, rolled or mounted to a nonplanar object. Although optimum effects are achieved when the neutral plane is located at the plane of device 5, advantages are clearly obtained even if the neutral plane is positioned only near photovoltaic device 5. In general, if the neutral plane is positioned near the plane of device 5, to within a distance of twenty percent of the overall thickness of solar cell tape 10 (i.e. the sum of thicknesses t_1 - t_4), significant advantages are obtained.

The neutral plane $\bar{y}$ of a multilayer article such as solar cell tape 10 is located using the principle of moments described by Equation 1.

$$\bar{y} = \frac{\sum E_i t_i y_i}{\sum E_i t_i} \quad \text{Eq. 1}$$

where:

- $\bar{y}$ = location of neutral plane;
- E_i = elastic modulus of layer i ;
- t_i = thickness of layer i ;
- y_i = distance of center of layer i from a reference point; and
- $\sum$ indicates summation over the i layers.

Using Equation 1, the neutral plane $\bar{y}$ of solar cell tape 10 with respect to photovoltaic device 5 (e.g. $\bar{y} = 0$ = center of device 5) is described by Equation 2.

$$\bar{y} = 0 = [E_1 t_1 (t_2 + t_1/2) + E_2 t_2 (t_2/2) - E_3 t_3 (t_3/2) - E_4 t_4 (t_3 + t_4/2)] / E_1 t_1 + E_2 t_2 + E_3 t_3 + E_4 t_4 \quad \text{Eq. 2}$$

Equation 2 is based upon the assumption that the thickness of photovoltaic device 5 is much less than any of thicknesses t_1 - t_4 . For neutral plane $\bar{y}$ to be located in the plane of photovoltaic device 5, e.g. between layers of adhesive 2 and substrate 3, the numerator in Equation 2 must be zero. This relationship can be described by Equation 3.

$$E_1 t_1 (t_2 + t_1/2) + E_2 t_2 (t_2/2) - E_3 t_3 (t_3/2) - E_4 t_4 (t_3 + t_4/2) = 0 \quad \text{Eq. 3}$$

Using Equation 3, t_1 - t_4 of layers of material 1-4 can be selected as a function of their respective elastic moduli E_1 - E_4 to place the neutral plane of solar cell tape 10 within the plane of photovoltaic device 5. Known manufacturing techniques such as those described above can be controlled to produce solar cell tape 10 with materials 1-4 having the selected thicknesses t_1 - t_4 , respectively.

A special case exists when elastic moduli E_1 , E_2 , and E_4 , of respective layers of material 1, 2 and 4 are equal to one another and much less than the elastic moduli E_3 of substrate 3, and the thicknesses t_1 , t_2 and t_4 of layers of material 1, 2 and 4 are substantially equal to a constant thickness t_c . In this case the thickness t_3 of substrate 3 which will place the neutral plane of solar cell tape 10 in the plane of photovoltaic device 5 can be computed as a function of elastic moduli E_c , E_3 and thickness t_c , as described in Equation

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$$t_3 = (3E_0/E_3) t_c \quad \text{Eq. 4}$$

5 where:

$$E_1 \approx E_2 \approx E_4 \approx E_0 \ll E_3$$

$$t_1 \approx t_2 \approx t_4 = t_c$$

Solar cell tape 20, which can also be manufactured in accordance with the present invention, is illustrated generally in Figure 2. Solar cell tape 20 includes a photovoltaic device 23 fabricated on substrate 22. Photovoltaic device 23 is encapsulated on the side opposite substrate 22 by a layer of transparent adhesive/glazing 21. Adhesive/glazing 21 is characterized by a flexural modulus E_{21} and a thickness t_{21} . Substrate 22 is characterized by a flexural modulus E_{22} and a thickness t_{22} . Substrate 22 and photovoltaic device 23 can be identical to their counterparts described with reference to solar cell tape 10. Pressure sensitive adhesives can be used for adhesive/glazing 21.

15 The position of neutral plane $\bar{y}$ of solar cell tape 20 is given by Equation 5.

$$\bar{y} = [E_{21}t_{21}(t_{21}/2) - E_{22}t_{22}(t_{22}/2)] / E_{21}t_{21} + E_{22}t_{22} \quad \text{Eq. 5}$$

Setting neutral plane $\bar{y}$ equal to zero, the position of the neutral plane with respect to the plane in which photovoltaic device 23 lies is described by Equation 6 below.

$$t_{22} = (E_{21}/E_{22}) t_{21} \quad \text{Eq. 6}$$

Solar cell tapes such as 10 and 20 manufactured in accordance with the present invention can be used in a wide variety of applications. In one embodiment solar cell tape 10 is used in conjunction with a light-rechargeable battery such as that described in US-application Serial No. 07/165,488, filed March 8, 1988 and assigned to the same assignee as the present invention. Other applications include light-powered decorator wall/outdoor clocks, calculators and other light-powered electronic device applications. Solar cell tape 20 can be adhesively secured to the interior of automotive or other glass and used to power a variety of electrical devices or rechargeable batteries. Since the neutral plane of these devices is located at the plane of the photovoltaic device, they can be rolled following manufacture and/or mounted to nonplanar objects without detrimentally affecting the physical and electrical characteristics of the device.

Claims

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1. Method of manufacturing an integrated circuit of the type having a flexible substrate comprising the successive deposition of a layer of semiconductor material on a flexible substrate and of an encapsulant layer over said layer of semiconductor material characterized by selecting thickness of the flexible substrate and/or encapsulant layer as a function of elastic moduli of the substrate and encapsulant layer so that the neutral stress/strain plane of the integrated circuit is located near the layer of the semiconductor material to prevent damaging stress on the layer of semiconductor material when the integrated circuit is flexed.
2. The method of claim 1 characterized by selecting thickness of the flexible substrate and/or encapsulant layer so that the neutral plane of the integrated circuit is located within twenty percent of an overall thickness of the integrated circuit from the layer of semiconductor material.
3. The method of claim 1 characterized by selecting thickness of the flexible substrate and/or encapsulant layer so that the neutral plane of the integrated circuit is located within five percent of an overall thickness of the integrated circuit from the layer of semiconductor material.
4. Method of manufacturing a solar cell tape (10) including depositing a thin-film photovoltaic device (5) on a flexible polymeric substrate (3), encapsulating the photovoltaic device with a layer of encapsulant (1,2), and applying a layer of adhesive (4) to the substrate opposite the photovoltaic device, characterized by selecting the thicknesses (t_3, t_1, t_2, t_4) of the substrate, layer of encapsulant and/or layer of adhesive as a function of their respective elastic moduli (E_3, E_1, E_2, E_4) to locate a neutral stress/strain plane of the solar cell tape near the photovoltaic device (5) to prevent damaging stress on the photovoltaic device when the solar cell tape (10) is flexed.

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4.

$$t_3 = (3E_C/E_3) t_c \quad \text{Eq. 4}$$

5 where:

$$E_1 \approx E_2 \approx E_4 \approx E_C \ll E_3$$

$$t_1 \approx t_2 \approx t_4 = t_c$$

Solar cell tape 20, which can also be manufactured in accordance with the present invention, is illustrated generally in Figure 2. Solar cell tape 20 includes a photovoltaic device 23 fabricated on substrate 22. Photovoltaic device 23 is encapsulated on the side opposite substrate 22 by a layer of transparent adhesive/glazing 21. Adhesive/glazing 21 is characterized by a flexural modulus E_{21} and a thickness t_{21} . Substrate 22 is characterized by a flexural modulus E_{22} and a thickness t_{22} . Substrate 22 and photovoltaic device 23 can be identical to their counterparts described with reference to solar cell tape 10. Pressure sensitive adhesives can be used for adhesive/glazing 21.

15 The position of neutral plane $\bar{y}$ of solar cell tape 20 is given by Equation 5.

$$\bar{y} = [E_{21} t_{21} (t_{21}/2) - E_{22} t_{22} (t_{22}/2)] / E_{21} t_{21} + E_{22} t_{22} \quad \text{Eq. 5}$$

Setting neutral plane $\bar{y}$ equal to zero, the position of the neutral plane with respect to the plane in which photovoltaic device 23 lies is described by Equation 6 below.

$$t_{22} = (E_{21}/E_{22}) t_{21} \quad \text{Eq. 6}$$

Solar cell tapes such as 10 and 20 manufactured in accordance with the present invention can be used in a wide variety of applications. In one embodiment solar cell tape 10 is used in conjunction with a light-rechargeable battery such as that described in US-application Serial No. 07/165,488, filed March 8, 1988 and assigned to the same assignee as the present invention. Other applications include light-powered decorator wall/outdoor clocks, calculators and other light-powered electronic device applications. Solar cell tape 20 can be adhesively secured to the interior of automotive or other glass and used to power a variety of electrical devices or rechargeable batteries. Since the neutral plane of these devices is located at the plane of the photovoltaic device, they can be rolled following manufacture and/or mounted to nonplanar objects without detrimentally affecting the physical and electrical characteristics of the device.

Claims

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1. Method of manufacturing an integrated circuit of the type having a flexible substrate comprising the successive deposition of a layer of semiconductor material on a flexible substrate and of an encapsulant layer over said layer of semiconductor material characterized by selecting thickness of the flexible substrate and/or encapsulant layer as a function of elastic moduli of the substrate and encapsulant layer so that the neutral stress/strain plane of the integrated circuit is located near the layer of the semiconductor material to prevent damaging stress on the layer of semiconductor material when the integrated circuit is flexed.
2. The method of claim 1 characterized by selecting thickness of the flexible substrate and/or encapsulant layer so that the neutral plane of the integrated circuit is located within twenty percent of an overall thickness of the integrated circuit from the layer of semiconductor material.
3. The method of claim 1 characterized by selecting thickness of the flexible substrate and/or encapsulant layer so that the neutral plane of the integrated circuit is located within five percent of an overall thickness of the integrated circuit from the layer of semiconductor material.
4. Method of manufacturing a solar cell tape (10) including depositing a thin-film photovoltaic device (5) on a flexible polymeric substrate (3), encapsulating the photovoltaic device with a layer of encapsulant (1,2), and applying a layer of adhesive (4) to the substrate opposite the photovoltaic device, characterized by selecting the thicknesses (t_3, t_1, t_2, t_4) of the substrate, layer of encapsulant and/or layer of adhesive as a function of their respective elastic moduli (E_3, E_1, E_2, E_4) to locate a neutral stress/strain plane of the solar cell tape near the photovoltaic device (5) to prevent damaging stress on the photovoltaic device when the solar cell tape (10) is flexed.



5. The method of claim 4 characterized by selecting the thicknesses of the flexible substrate, layer of encapsulant and/or layer of adhesive so that the neutral plane of the solar cell tape is located within twenty percent of an overall thickness of the solar cell tape from the photovoltaic device.
- 5 6. The method of claim 4 characterized by selecting the thicknesses of the flexible substrate, layer of encapsulant and/or layer of adhesive so that the neutral plane of the solar cell tape is located within five percent of an overall thickness of the solar cell tape from the photovoltaic device.
7. A flexible integrated circuit including:
 10 a flexible substrate;
 a layer of semiconductor material on said flexible substrate; and
 an encapsulant layer, deposited over said layer of semiconductor material substrate, characterized in that the thicknesses and elastic moduli of the substrate and of the encapsulant layer are such that the neutral stress/strain plane of the integrated circuit is located near the layer of the semiconductor material to prevent damaging stress on the layer of semiconductor material when the integrated circuit is flexed.
- 15 8. The integrated circuit of claim 7 wherein the neutral plane is located within ten percent of the overall thickness of the integrated circuit from the layer of semiconductor material.
- 20 9. The method of claim 8 wherein the neutral plane of the integrated circuit is located within five percent of the overall thickness of the integrated circuit from the layer of semiconductor material.
10. A strip of solar cell tape (10) including:
 25 a flexible polymeric substrate (3);
 a thin-film photovoltaic device (5) on the substrate;
 a layer of encapsulant (1,2) encapsulating the photovoltaic device; and
 a layer of adhesive deposited on the substrate on the side opposite the photovoltaic device, characterized in that the thicknesses and elastic moduli of the substrate (t_3, E_3), layer of encapsulant (t_1, t_2, E, E_2) and layer of adhesive (t_4, E_4) are such that the neutral stress/strain plane of the solar cell tape is located near the thin film photovoltaic device (5) to prevent damaging stress on the photovoltaic device when the solar cell tape is flexed.
- 30 11. The solar cell tape of claim 10 wherein the neutral plane is located within ten percent of an overall thickness of the tape from the photovoltaic device.
- 35 12. The solar cell tape of claim 10 wherein the neutral plane is located within five percent of an overall thickness of the tape from the photovoltaic device.

40 Patentansprüche

1. Verfahren zur Herstellung einer integrierten Schaltung des Typs mit flexiblem Substrat, bei dem nacheinander eine Schicht Halbleitermaterial auf ein flexibles Substrat und eine Kapselungsschicht auf diese Schicht aus Halbleitermaterial aufgetragen werden, dadurch gekennzeichnet, daß die Dicke des flexiblen Substrats und/oder der Kapselungsschicht in Abhängigkeit von den Elastizitätsmodulen des Substrats und der Kapselungsschicht gewählt ist, so daß die neutrale Zug-/Spannungsebene der integrierten Schaltung in der Nähe der Halbleitermaterialsicht zu liegen kommt, um zu verhindern, daß die Halbleitermaterialsicht durch Spannungen beschädigt wird, wenn die integrierte Schaltung gebogen wird.
- 45 2. Verfahren nach Anspruch 1, dadurch gekennzeichnet, daß die Dicke des flexiblen Substrats und/oder der Kapselungsschicht so gewählt ist, daß die neutrale Ebene der integrierten Schaltung innerhalb von 20% der Gesamtdicke der integrierten Schaltung entfernt von der Halbleitermaterialsicht zu liegen kommt.
- 50 3. Verfahren nach Anspruch 1, dadurch gekennzeichnet, daß die Dicke des flexiblen Substrats und/oder der Kapselungsschicht so gewählt ist, daß die neutrale Ebene der integrierten Schaltung innerhalb von 5% der Gesamtdicke der integrierten Schaltung entfernt von der Halbleitermaterialsicht zu liegen
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kommt.

4. Verfahren zur Herstellung eines Sonnenzellenbandes (10), das folgende Schritte umfaßt: Auftragen eines dünnen Sperrschichtelements (5) auf ein flexibles polymeres Substrat (3), Kapseln des Sperrschichtelements mit einer Kapselungsschicht (1, 2) und Auftragen einer Klebstoffschicht (4) auf das dem Sperrschichtelement gegenüberliegende Substrat, dadurch gekennzeichnet, daß die Dicken (t_3 , t_1 , t_2 , t_4) des Substrats, der Kapselungsschicht und/oder der Klebstoffschicht in Abhängigkeit von ihren jeweiligen Elastizitätsmoduln (E_3 , E_1 , E_2 , E_4) gewählt werden, um eine neutrale Zug-/Spannungsebene des Sonnenzellenbandes in der Nähe des Sperrschichtelements (5) anzuordnen, wodurch verhindert wird, daß das Sperrschichtelement durch Spannungen beschädigt wird, wenn das Sonnenzellenband (10) gebogen wird.
5. Verfahren nach Anspruch 4, dadurch gekennzeichnet, daß die Dicken des flexiblen Substrats, der Kapselungsschicht und/oder der Klebstoffschicht so gewählt sind, daß die neutrale Ebene des Sonnenzellenbandes innerhalb von 20% der Gesamtdicke des Sonnenzellenbandes entfernt vom Sperrschichtelement zu liegen kommt.
6. Verfahren nach Anspruch 4, dadurch gekennzeichnet, daß die Dicken des flexiblen Substrats, der Kapselungsschicht und/oder der Klebstoffschicht so gewählt sind, daß die neutrale Ebene des Sonnenzellenbandes innerhalb von 5% der Gesamtdicke des Sonnenzellenbandes entfernt vom Sperrschichtelement zu liegen kommt.
7. Flexible integrierte Schaltung umfassend:
 - ein flexibles Substrat;
 - eine Schicht Halbleitermaterial auf dem flexiblen Substrat; und
 - eine Kapselungsschicht, die auf diese Halbleitermaterialsicht aufgetragen ist, dadurch gekennzeichnet, daß die Dicken und Elastizitätsmoduln des Substrats und der Kapselungsschicht so gewählt sind, daß die neutrale Zug-/Spannungsebene im Bereich der Halbleitermaterialsicht zu liegen kommt, um zu verhindern, daß die Halbleitermaterialsicht durch Spannungen beschädigt wird, wenn die integrierte Schaltung gebogen wird.
8. Integrierte Schaltung nach Anspruch 7, dadurch gekennzeichnet, daß die neutrale Ebene innerhalb von 10% der Gesamtdicke der integrierten Schaltung entfernt von der Halbleitermaterialsicht zu liegen kommt.
9. Integrierte Schaltung nach Anspruch 8, dadurch gekennzeichnet, daß die neutrale Ebene innerhalb von 5% der Gesamtdicke der integrierten Schaltung entfernt von der Halbleitermaterialsicht zu liegen kommt.
10. Streifen eines Sonnenzellenbandes (10) umfassend:
 - ein flexibles polymeres Substrat (3);
 - ein dünnes Sperrschichtelement (5) auf dem Substrat;
 - eine das Sperrschichtelement kapselnde Kapselungsschicht (1, 2); und
 - eine auf dem Substrat auf der Seite gegenüber dem Sperrschichtelement aufgetragene Klebstoffschicht (4), dadurch gekennzeichnet, daß die Dicken und Elastizitätsmoduln des Substrats (t_3 , E_3), der Kapselungsschicht (t_1 , t_2 , E_1 , E_2) und der Klebstoffschicht (t_4 , E_4) so gewählt sind, daß die neutrale Zug-/Spannungsebene des Sonnenzellenbandes im Bereich des dünnen Sperrschichtelements (5) zu liegen kommt, um zu verhindern, daß das Sperrschichtelement durch Spannungen beschädigt wird, wenn das Sonnenzellenband gebogen wird.
11. Sonnenzellenband nach Anspruch 10, dadurch gekennzeichnet, daß die neutrale Ebene innerhalb von 10% der Gesamtdicke des Bandes entfernt vom Sperrschichtelement zu liegen kommt.
12. Sonnenzellenband nach Anspruch 11, dadurch gekennzeichnet, daß die neutrale Ebene innerhalb von 5% der Gesamtdicke des Bandes entfernt vom Sperrschichtelement zu liegen kommt.



Revendications

1. Procédé de fabrication d'un circuit intégré du type ayant un substrat souple, comprenant le dépôt successif d'une couche d'un matériau semi-conducteur sur un substrat souple et d'une couche d'encapsulation sur ladite couche de matériau semi-conducteur, caractérisé en ce que l'on choisit l'épaisseur du substrat souple et/ou de la couche d'encapsulation en fonction des modules élastiques du substrat et de la couche d'encapsulation, de façon à ce que le plan neutre de contrainte/déformation du circuit intégré soit situé près de la couche du matériau semi-conducteur, pour éviter une contrainte endommageant la couche de matériau semi-conducteur lorsque le circuit intégré est fléchi.
2. Procédé selon la revendication 1, caractérisé par le choix de l'épaisseur du substrat souple et/ou de la couche d'encapsulation de façon à ce que le plan neutre du circuit intégré soit situé à moins de 20 % d'une épaisseur globale du circuit intégré à partir de la couche de matériau semi-conducteur.
3. Procédé selon la revendication 1, caractérisé par le choix de l'épaisseur du substrat souple et/ou de la couche d'encapsulation de façon à ce que le plan neutre du circuit intégré soit situé à moins de 5 % d'une épaisseur globale du circuit intégré à partir de la couche de matériau semi-conducteur.
4. Procédé de fabrication d'un ruban de cellule solaire (10) comprenant le dépôt d'un dispositif photovoltaïque en pellicule mince (5) sur un substrat polymère souple (3), l'encapsulation du dispositif photovoltaïque avec une couche d'encapsulation (1, 2) et l'application d'une couche d'adhésif (4) au substrat à l'opposé du dispositif photovoltaïque, caractérisé par le choix des épaisseurs (t_3 , t_1 , t_2 et t_4) du substrat, de la couche d'encapsulation et/ou de la couche d'adhésif en fonction de leurs modules élastiques respectifs (E_3 , E_1 , E_2 et E_4) pour localiser un plan neutre de contrainte/déformation du ruban de cellule solaire près du dispositif photovoltaïque (5) pour éviter une contrainte endommageant le dispositif photovoltaïque lorsque le ruban de cellule solaire (10) est fléchi.
5. Procédé selon la revendication 4, caractérisé par le choix des épaisseurs du substrat souple, de la couche d'encapsulation et/ou de la couche d'adhésif afin que le plan neutre du ruban de cellule solaire soit situé à moins de 20 % de l'épaisseur globale du ruban de cellule solaire à partir du dispositif photovoltaïque.
6. Procédé selon la revendication 4, caractérisé par le choix des épaisseurs du substrat souple, de la couche d'encapsulation et/ou de la couche d'adhésif afin que le plan neutre du ruban de cellule solaire soit situé à moins de 5 % de l'épaisseur globale du ruban de cellule solaire à partir du dispositif photovoltaïque.
7. Circuit intégré souple comprenant :
un substrat souple ;
une couche de matériau semi-conducteur sur ledit substrat souple ; et
une couche d'encapsulation déposée sur ladite couche de matériau semi-conducteur,
caractérisé en ce que les épaisseurs et les modules élastiques du substrat et de la couche d'encapsulation sont tels que le plan neutre de contrainte/déformation du circuit intégré soit situé près de la couche du matériau semi-conducteur pour éviter une contrainte endommageant la couche de matériau semi-conducteur lorsque le circuit intégré est fléchi.
8. Circuit intégré selon la revendication 7, dans lequel le plan neutre est situé à moins de 10 % de l'épaisseur global du circuit intégré à partir de la couche de matériau semi-conducteur.
9. Circuit selon la revendication 8, dans lequel le plan neutre du circuit intégré est situé à moins de 5 % de l'épaisseur globale du circuit intégré à partir de la couche de matériau semi-conducteur.
10. Bande de ruban de cellule solaire (10) comprenant :
un substrat polymère souple (3) ;
un dispositif photovoltaïque en pellicule mince (5) sur le substrat ;
une couche d'encapsulation (1, 2) encapsulant le dispositif photovoltaïque ; et
une couche d'adhésif déposée sur le substrat du côté opposé au dispositif photovoltaïque,
caractérisée en ce que les épaisseurs et les modules élastiques du substrat (t_3 , E_3), de la couche



d'encapsulation (t_1 , t_2 , E_1 , E_2) et de la couche d'adhésif (t_4 , E_4) sont tels que le plan neutre de contrainte/déformation du ruban de cellule solaire soit situé près du dispositif photovoltaïque en pellicule mince (5) pour éviter une contrainte endommageant le dispositif photovoltaïque lorsque le ruban de cellule solaire est fléchi.

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11. Ruban de cellule solaire selon la revendication 10, dans lequel le plan neutre est situé à moins de 10 % de l'épaisseur globale du ruban à partir du dispositif photovoltaïque.
12. Ruban de cellule solaire selon la revendication 10, dans lequel le plan neutre est situé à moins de 5 % de l'épaisseur globale du ruban à partir du dispositif photovoltaïque.

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